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Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I ² C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08dv16mlc

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Chapter 12

Freescale Controller Area Network (S08MSCANV1)

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security; the other three combinations engage security. Notice the erased state (1:1) makes the MCU secure. During development, whenever the Flash is erased, it is good practice to immediately program the SEC0 bit to 0 in NVOPT so SEC = 1:0. This would allow the MCU to remain unsecured after a subsequent reset.

The on-chip debug module cannot be enabled while the MCU is secure. The separate background debug controller can be used for background memory access commands, but the MCU cannot enter active background mode except by holding BKGD low at the rising edge of reset.

A user can choose to allow or disallow a security unlocking mechanism through an 8-byte backdoor security key. If the nonvolatile KEYEN bit in NVOPT/FOPT is 0, the backdoor key is disabled and there is no way to disengage security without completely erasing all Flash locations. If KEYEN is 1, a secure user program can temporarily disengage security by:

1. Writing 1 to KEYACC in the FCNFG register. This makes the Flash module interpret writes to the backdoor comparison key locations (NVBACKKEY through NVBACKKEY+7) as values to be compared against the key rather than as the first step in a Flash program or erase command.
2. Writing the user-entered key values to the NVBACKKEY through NVBACKKEY+7 locations. These writes must be performed in order starting with the value for NVBACKKEY and ending with NVBACKKEY+7. STHX must not be used for these writes because these writes cannot be performed on adjacent bus cycles. User software normally would get the key codes from outside the MCU system through a communication interface such as a serial I/O.
3. Writing 0 to KEYACC in the FCNFG register. If the 8-byte key that was written matches the key stored in the Flash locations, SEC bits are automatically changed to 1:0 and security will be disengaged until the next reset.

The security key can be written only from secure memory (either RAM or Flash), so it cannot be entered through background commands without the cooperation of a secure user program.

The backdoor comparison key (NVBACKKEY through NVBACKKEY+7) is located in Flash memory locations in the nonvolatile register space so users can program these locations exactly as they would program any other Flash memory location. The nonvolatile registers are in the same 768-byte block of Flash as the reset and interrupt vectors, so block protecting that space also block protects the backdoor comparison key. Block protects cannot be changed from user application programs, so if the vector space is block protected, the backdoor security key mechanism cannot permanently change the block protect, security settings, or the backdoor key.

Security can always be disengaged through the background debug interface by taking these steps:

1. Disable any block protections by writing FPROT. FPROT can be written only with background debug commands, not from application software.
2. Mass erase Flash if necessary.
3. Blank check Flash. Provided Flash is completely erased, security is disengaged until the next reset.

To avoid returning to secure mode after the next reset, program NVOPT so SEC = 1:0.

Chapter 6

Parallel Input/Output Control

This section explains software controls related to parallel input/output (I/O) and pin control. The MC9S08DV60 Series has seven parallel I/O ports which include a total of up to 53 I/O pins and one input-only pin. See [Chapter 2, “Pins and Connections,”](#) for more information about pin assignments and external hardware considerations of these pins.

Many of these pins are shared with on-chip peripherals such as timer systems, communication systems, or pin interrupts as shown in [Table 2-1](#). The peripheral modules have priority over the general-purpose I/O functions so that when a peripheral is enabled, the I/O functions associated with the shared pins are disabled.

After reset, the shared peripheral functions are disabled and the pins are configured as inputs ($PTxDDn = 0$). The pin control functions for each pin are configured as follows: slew rate control enabled ($PTxSEn = 1$), low drive strength selected ($PTxDSn = 0$), and internal pull-ups disabled ($PTxPEn = 0$).

NOTE

- Not all general-purpose I/O pins are available on all packages. To avoid extra current drain from floating input pins, the user’s reset initialization routine in the application program must either enable on-chip pull-up devices or change the direction of unconnected pins to outputs so the pins do not float.
- The PTE1 pin does not contain a clamp diode to V_{DD} and should not be driven above V_{DD} . The voltage measured on the internally pulled up PTE1 pin may be as low as $V_{DD} - 0.7$ V. The internal gates connected to this pin are pulled all the way to V_{DD} .

6.1 Port Data and Data Direction

Reading and writing of parallel I/Os are performed through the port data registers. The direction, either input or output, is controlled through the port data direction registers. The parallel I/O port function for an individual pin is illustrated in the block diagram shown in [Figure 6-1](#).

The data direction control bit ($PTxDDn$) determines whether the output buffer for the associated pin is enabled, and also controls the source for port data register reads. The input buffer for the associated pin is always enabled unless the pin is enabled as an analog function or is an output-only pin.

When a shared digital function is enabled for a pin, the output buffer is controlled by the shared function. However, the data direction register bit will continue to control the source for reads of the port data register.

When a shared analog function is enabled for a pin, both the input and output buffers are disabled. A value of 0 is read for any port data bit where the bit is an input ($PTxDDn = 0$) and the input buffer is disabled.

6.5.2 Port B Registers

Port B is controlled by the registers listed below.

6.5.2.1 Port B Data Register (PTBD)

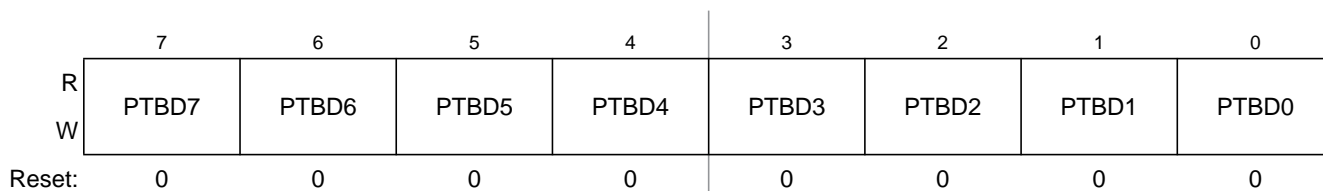


Figure 6-11. Port B Data Register (PTBD)

Table 6-9. PTBD Register Field Descriptions

Field	Description
7:0 PTBD[7:0]	<p>Port B Data Register Bits — For port B pins that are inputs, reads return the logic level on the pin. For port B pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port B pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTBD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups/pull-downs disabled.</p>

6.5.2.2 Port B Data Direction Register (PTBDD)

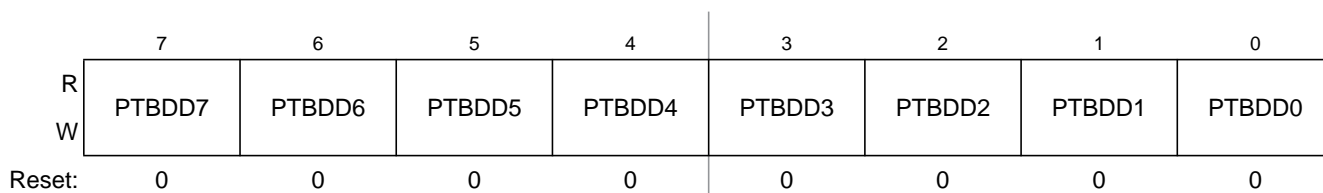


Figure 6-12. Port B Data Direction Register (PTBDD)

Table 6-10. PTBDD Register Field Descriptions

Field	Description
7:0 PTBDD[7:0]	<p>Data Direction for Port B Bits — These read/write bits control the direction of port B pins and what is read for PTBD reads.</p> <p>0 Input (output driver disabled) and reads return the pin value.</p> <p>1 Output driver enabled for port B bit n and PTBD reads return the contents of PTBDn.</p>

6.5.4.5 Port D Drive Strength Selection Register (PTDDS)

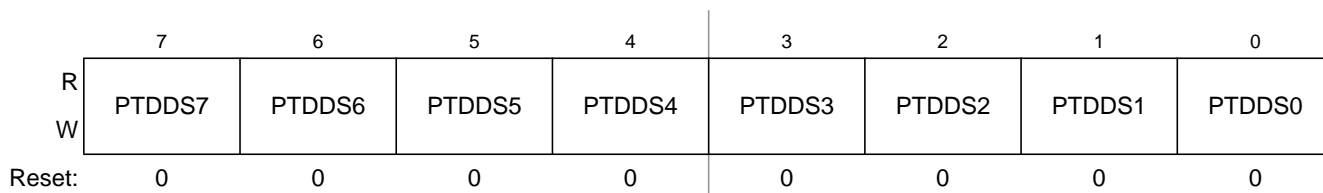


Figure 6-28. Drive Strength Selection for Port D Register (PTDDS)

Table 6-26. PTDDS Register Field Descriptions

Field	Description
7:0 PTDDS[7:0]	Output Drive Strength Selection for Port D Bits — Each of these control bits selects between low and high output drive for the associated PTD pin. For port D pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port D bit n. 1 High output drive strength selected for port D bit n.

6.5.4.6 Port D Interrupt Status and Control Register (PTDSC)

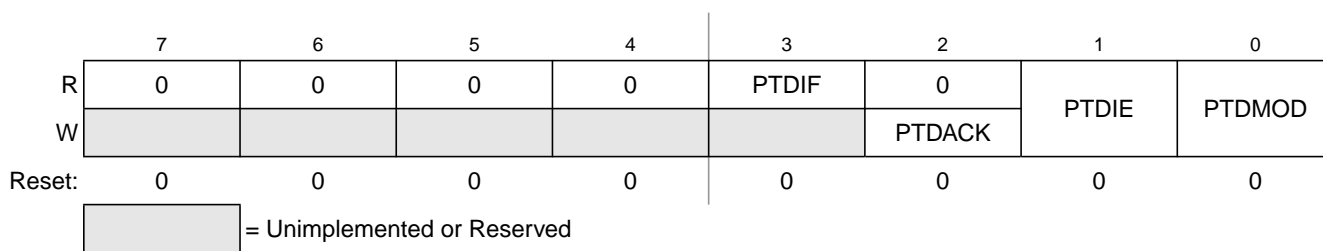


Figure 6-29. Port D Interrupt Status and Control Register (PTDSC)

Table 6-27. PTDSC Register Field Descriptions

Field	Description
3 PTDIF	Port D Interrupt Flag — PTDIF indicates when a port D interrupt is detected. Writes have no effect on PTDIF. 0 No port D interrupt detected. 1 Port D interrupt detected.
2 PTDACK	Port D Interrupt Acknowledge — Writing a 1 to PTDACK is part of the flag clearing mechanism. PTDACK always reads as 0.
1 PTDIE	Port D Interrupt Enable — PTDIE determines whether a port D interrupt is requested. 0 Port D interrupt request not enabled. 1 Port D interrupt request enabled.
0 PTDMOD	Port A Detection Mode — PTDMOD (along with the PTDES bits) controls the detection mode of the port D interrupt pins. 0 Port D pins detect edges only. 1 Port D pins detect both edges and levels.

Table 7-2. Instruction Set Summary (Sheet 4 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR	
						V 1 1 H	I N Z C
CMP #opr8i CMP opr8a CMP opr16a CMP oprx16,X CMP oprx8,X CMP ,X CMP oprx16,SP CMP oprx8,SP	Compare Accumulator with Memory A – M (CCR Updated But Operands Not Changed)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A1 ii B1 dd C1 hh ll D1 ee ff E1 ff F1 9E D1 ee ff 9E E1 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	↑ 1 1 –	– ↓ ↓ ↓ ↓
COM opr8a COMA COMX COM oprx8,X COM ,X COM oprx8,SP	Complement (One's Complement) $M \leftarrow (\bar{M}) = \$FF - (M)$ $A \leftarrow (\bar{A}) = \$FF - (A)$ $X \leftarrow (\bar{X}) = \$FF - (X)$ $M \leftarrow (\bar{M}) = \$FF - (M)$ $M \leftarrow (\bar{M}) = \$FF - (M)$ $M \leftarrow (\bar{M}) = \$FF - (M)$	DIR INH INH IX1 IX SP1	33 dd 43 53 63 ff 73 9E 63 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	0 1 1 –	– ↓ ↓ ↓ 1
CPHX opr16a CPHX #opr16i CPHX opr8a CPHX oprx8,SP	Compare Index Register (H:X) with Memory (H:X) – (M:M + \$0001) (CCR Updated But Operands Not Changed)	EXT IMM DIR SP1	3E hh ll 65 jj kk 75 dd 9E F3 ff	6 3 5 6	prrfpp ppp rrfpp prrfpp	↑ 1 1 –	– ↓ ↓ ↓ ↓
CPX #opr8i CPX opr8a CPX opr16a CPX oprx16,X CPX oprx8,X CPX ,X CPX oprx16,SP CPX oprx8,SP	Compare X (Index Register Low) with Memory X – M (CCR Updated But Operands Not Changed)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A3 ii B3 dd C3 hh ll D3 ee ff E3 ff F3 9E D3 ee ff 9E E3 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	↑ 1 1 –	– ↓ ↓ ↓ ↓
DAA	Decimal Adjust Accumulator After ADD or ADC of BCD Values	INH	72	1	p	U 1 1 –	– ↓ ↓ ↓ ↓
DBNZ opr8a,rel DBNZA rel DBNZX rel DBNZ oprx8,X,rel DBNZ ,X,rel DBNZ oprx8,SP,rel	Decrement A, X, or M and Branch if Not Zero (if (result) ≠ 0) DBNZX Affects X Not H	DIR INH INH IX1 IX SP1	3B dd rr 4B rr 5B rr 6B ff rr 7B rr 9E 6B ff rr	7 4 4 7 6 8	rfwpppp fppp fppp rfwpppp rfwppp prfwpppp	– 1 1 –	– – – –
DEC opr8a DECA DECX DEC oprx8,X DEC ,X DEC oprx8,SP	Decrement $M \leftarrow (M) - \$01$ $A \leftarrow (A) - \$01$ $X \leftarrow (X) - \$01$ $M \leftarrow (M) - \$01$ $M \leftarrow (M) - \$01$ $M \leftarrow (M) - \$01$	DIR INH INH IX1 IX SP1	3A dd 4A 5A 6A ff 7A 9E 6A ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↑ 1 1 –	– ↓ ↓ ↓ –
DIV	Divide $A \leftarrow (H:A) \div (X); H \leftarrow \text{Remainder}$	INH	52	6	fffffp	– 1 1 –	– – ↓ ↓
EOR #opr8i EOR opr8a EOR opr16a EOR oprx16,X EOR oprx8,X EOR ,X EOR oprx16,SP EOR oprx8,SP	Exclusive OR Memory with Accumulator $A \leftarrow (A \oplus M)$	IMM DIR EXT IX2 IX1 IX SP2 SP1	A8 ii B8 dd C8 hh ll D8 ee ff E8 ff F8 9E D8 ee ff 9E E8 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 –	– ↓ ↓ ↓ –

8.1.1 Features

Key features of the MCG module are:

- Frequency-locked loop (FLL)
 - 0.2% resolution using internal 32-kHz reference
 - 2% deviation over voltage and temperature using internal 32-kHz reference
 - Internal or external reference can be used to control the FLL
- Phase-locked loop (PLL)
 - Voltage-controlled oscillator (VCO)
 - Modulo VCO frequency divider
 - Phase/Frequency detector
 - Integrated loop filter
 - Lock detector with interrupt capability
- Internal reference clock
 - Nine trim bits for accuracy
 - Can be selected as the clock source for the MCU
- External reference clock
 - Control for external oscillator
 - Clock monitor with reset capability
 - Can be selected as the clock source for the MCU
- Reference divider is provided
- Clock source selected can be divided down by 1, 2, 4, or 8
- BDC clock (MCGLCLK) is provided as a constant divide by 2 of the DCO output whether in an FLL or PLL mode.

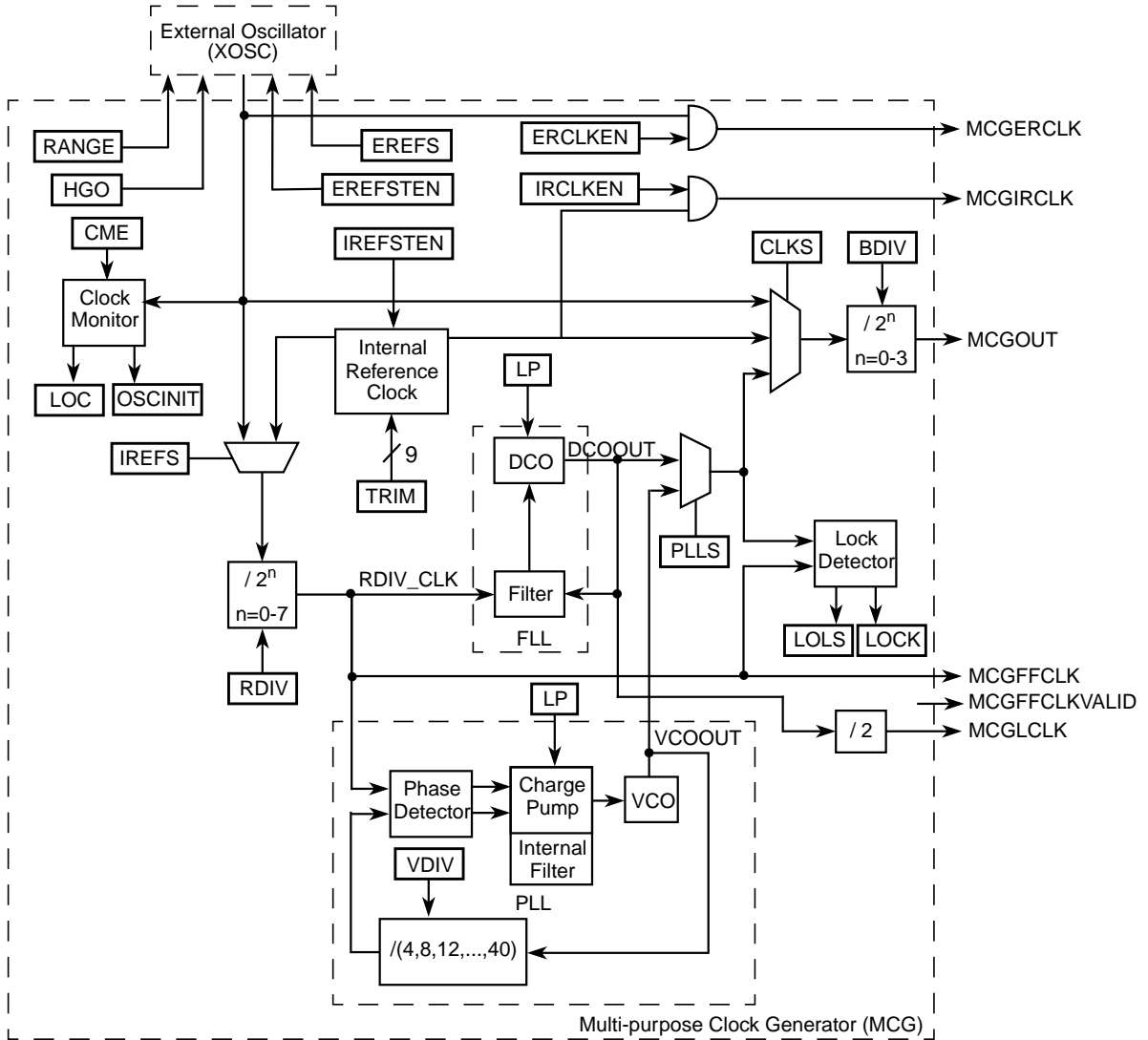


Figure 8-2. Multi-Purpose Clock Generator (MCG) Block Diagram

8.4.3 Bus Frequency Divider

The BDIV bits can be changed at anytime and the actual switch to the new frequency will occur immediately.

8.4.4 Low Power Bit Usage

The low power bit (LP) is provided to allow the FLL or PLL to be disabled and thus conserve power when these systems are not being used. However, in some applications it may be desirable to enable the FLL or PLL and allow it to lock for maximum accuracy before switching to an engaged mode. Do this by writing the LP bit to 0.

8.4.5 Internal Reference Clock

When IRCLKEN is set the internal reference clock signal will be presented as MCGIRCLK, which can be used as an additional clock source. The MCGIRCLK frequency can be re-targeted by trimming the period of the internal reference clock. This can be done by writing a new value to the TRIM bits in the MCGTRM register. Writing a larger value will decrease the MCGIRCLK frequency, and writing a smaller value to the MCGTRM register will increase the MCGIRCLK frequency. The TRIM bits will effect the MCGOUT frequency if the MCG is in FLL engaged internal (FEI), FLL bypassed internal (FBI), or bypassed low power internal (BLPI) mode. The TRIM and FTRIM value is initialized by POR but is not affected by other resets.

Until MCGIRCLK is trimmed, programming low reference divider (RDIV) factors may result in MCGOUT frequencies that exceed the maximum chip-level frequency and violate the chip-level clock timing specifications (see the [Device Overview](#) chapter).

If IREFSTEN and IRCLKEN bits are both set, the internal reference clock will keep running during stop mode in order to provide a fast recovery upon exiting stop.

8.4.6 External Reference Clock

The MCG module can support an external reference clock with frequencies between 31.25 kHz to 5 MHz in FEE and FBE modes, 1 MHz to 16 MHz in PEE and PBE modes, and 0 to 40 MHz in BLPE mode.

When ERCLKEN is set, the external reference clock signal will be presented as MCGERCLK, which can be used as an additional clock source. When IREFS = 1, the external reference clock will not be used by the FLL or PLL and will only be used as MCGERCLK. In these modes, the frequency can be equal to the maximum frequency the chip-level timing specifications will support (see the [Device Overview](#) chapter).

If EREFSTEN and ERCLKEN bits are both set or the MCG is in FEE, FBE, PEE, PBE or BLPE mode, the external reference clock will keep running during stop mode in order to provide a fast recovery upon exiting stop.

If CME bit is written to 1, the clock monitor is enabled. If the external reference falls below a certain frequency (f_{loc_high} or f_{loc_low} depending on the RANGE bit in the MCGC2), the MCU will reset. The LOC bit in the System Reset Status (SRS) register will be set to indicate the error.

10.6.2.3 Noise-Induced Errors

System noise that occurs during the sample or conversion process can affect the accuracy of the conversion. The ADC accuracy numbers are guaranteed as specified only if the following conditions are met:

- There is a 0.1 μF low-ESR capacitor from V_{REFH} to V_{REFL} .
- There is a 0.1 μF low-ESR capacitor from V_{DDAD} to V_{SSAD} .
- If inductive isolation is used from the primary supply, an additional 1 μF capacitor is placed from V_{DDAD} to V_{SSAD} .
- V_{SSAD} (and V_{REFL} , if connected) is connected to V_{SS} at a quiet point in the ground plane.
- Operate the MCU in wait or stop3 mode before initiating (hardware triggered conversions) or immediately after initiating (hardware or software triggered conversions) the ADC conversion.
 - For software triggered conversions, immediately follow the write to ADCSC1 with a wait instruction or stop instruction.
 - For stop3 mode operation, select ADACK as the clock source. Operation in stop3 reduces V_{DD} noise but increases effective conversion time due to stop recovery.
- There is no I/O switching, input or output, on the MCU during the conversion.

There are some situations where external system activity causes radiated or conducted noise emissions or excessive V_{DD} noise is coupled into the ADC. In these situations, or when the MCU cannot be placed in wait or stop3 or I/O activity cannot be halted, these recommended actions may reduce the effect of noise on the accuracy:

- Place a 0.01 μF capacitor (C_{AS}) on the selected input channel to V_{REFL} or V_{SSAD} (this improves noise issues, but affects the sample rate based on the external analog source resistance).
- Average the result by converting the analog input many times in succession and dividing the sum of the results. Four samples are required to eliminate the effect of a 1LSB, one-time error.
- Reduce the effect of synchronous noise by operating off the asynchronous clock (ADACK) and averaging. Noise that is synchronous to ADCK cannot be averaged out.

10.6.2.4 Code Width and Quantization Error

The ADC quantizes the ideal straight-line transfer function into 4096 steps (in 12-bit mode). Each step ideally has the same height (1 code) and width. The width is defined as the delta between the transition points to one code and the next. The ideal code width for an N bit converter (in this case N can be 8, 10 or 12), defined as 1LSB, is:

$$1 \text{ lsb} = (V_{\text{REFH}} - V_{\text{REFL}}) / 2^N \quad \text{Eqn. 10-2}$$

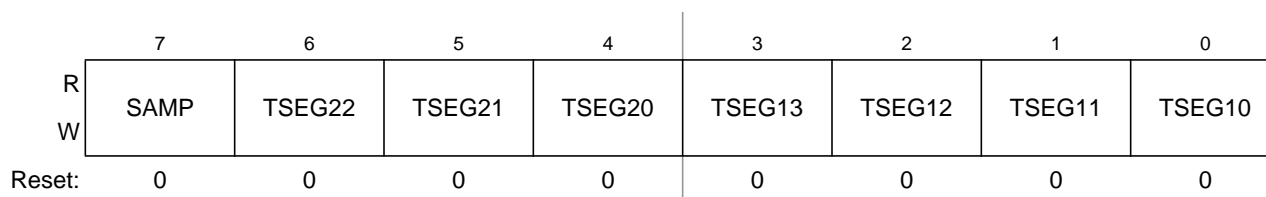
There is an inherent quantization error due to the digitization of the result. For 8-bit or 10-bit conversions the code transitions when the voltage is at the midpoint between the points where the straight line transfer function is exactly represented by the actual transfer function. Therefore, the quantization error will be $\pm 1/2$ lsb in 8- or 10-bit mode. As a consequence, however, the code width of the first (0x000) conversion is only 1/2 lsb and the code width of the last (0xFF or 0x3FF) is 1.5 lsb.

Table 12-5. Baud Rate Prescaler

BRP5	BRP4	BRP3	BRP2	BRP1	BRP0	Prescaler value (P)
0	0	0	0	0	0	1
0	0	0	0	0	1	2
0	0	0	0	1	0	3
0	0	0	0	1	1	4
:	:	:	:	:	:	:
1	1	1	1	1	1	64

12.3.4 MSCAN Bus Timing Register 1 (CANBTR1)

The CANBTR1 register configures various CAN bus timing parameters of the MSCAN module.


Figure 12-7. MSCAN Bus Timing Register 1 (CANBTR1)

Read: Anytime

Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1)

Table 12-6. CANBTR1 Register Field Descriptions

Field	Description
7 SAMP	Sampling — This bit determines the number of CAN bus samples taken per bit time. 0 One sample per bit. 1 Three samples per bit ¹ . If SAMP = 0, the resulting bit value is equal to the value of the single bit positioned at the sample point. If SAMP = 1, the resulting bit value is determined by using majority rule on the three total samples. For higher bit rates, it is recommended that only one sample is taken per bit time (SAMP = 0).
6:4 TSEG2[2:0]	Time Segment 2 — Time segments within the bit time fix the number of clock cycles per bit time and the location of the sample point (see Figure 12-43). Time segment 2 (TSEG2) values are programmable as shown in Table 12-7 .
3:0 TSEG1[3:0]	Time Segment 1 — Time segments within the bit time fix the number of clock cycles per bit time and the location of the sample point (see Figure 12-43). Time segment 1 (TSEG1) values are programmable as shown in Table 12-8 .

¹ In this case, PHASE_SEG1 must be at least 2 time quanta (Tq).

12.3.9 MSCAN Transmitter Message Abort Acknowledge Register (CANTAAK)

The CANTAAK register indicates the successful abort of messages queued for transmission, if requested by the appropriate bits in the CANTARQ register.

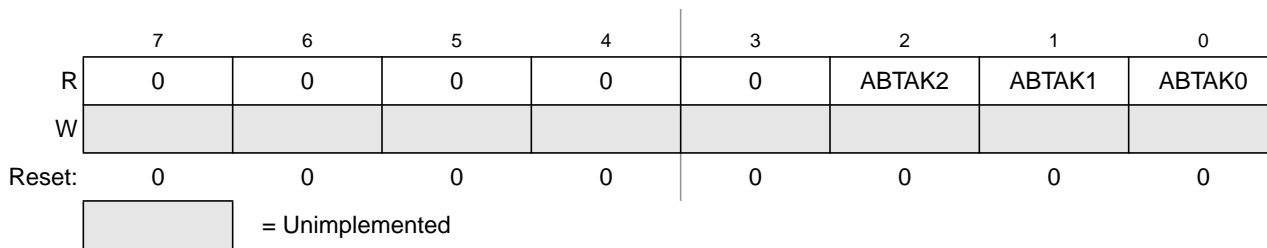


Figure 12-13. MSCAN Transmitter Message Abort Acknowledge Register (CANTAAK)

NOTE

The CANTAAK register is held in the reset state when the initialization mode is active (INTRQ = 1 and INITAK = 1).

Read: Anytime

Write: Unimplemented for ABTAKx flags

Table 12-14. CANTAAK Register Field Descriptions

Field	Description
2:0 ABTAK[2:0]	<p>Abort Acknowledge — This flag acknowledges that a message was aborted due to a pending transmission abort request from the CPU. After a particular message buffer is flagged empty, this flag can be used by the application software to identify whether the message was aborted successfully or was sent anyway. The ABTAKx flag is cleared whenever the corresponding TXE flag is cleared.</p> <p>0 The message was not aborted. 1 The message was aborted.</p>

12.3.10 MSCAN Transmit Buffer Selection Register (CANTBSEL)

The CANTBSEL selections of the actual transmit message buffer, which is accessible in the CANTXFG register space.

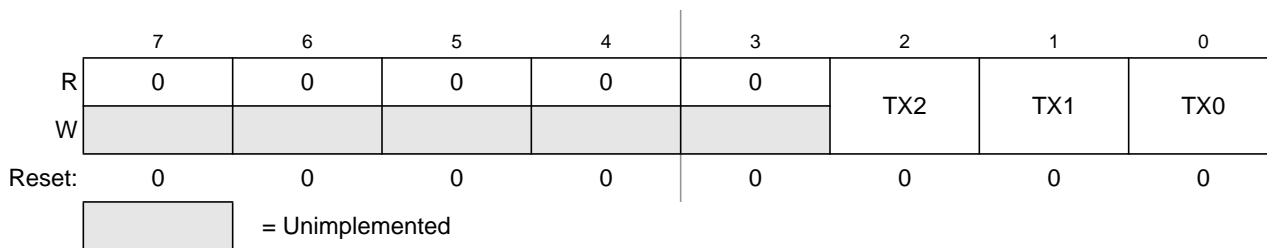


Figure 12-14. MSCAN Transmit Buffer Selection Register (CANTBSEL)

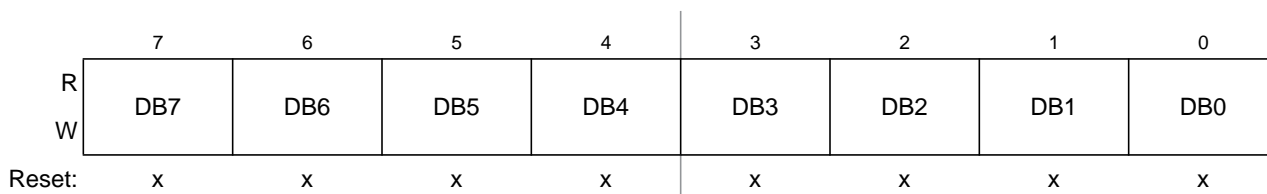


Figure 12-33. Data Segment Registers (DSR0–DSR7) — Extended Identifier Mapping

Table 12-31. DSR0–DSR7 Register Field Descriptions

Field	Description
7:0 DB[7:0]	Data bits 7:0

12.4.4 Data Length Register (DLR)

This register keeps the data length field of the CAN frame.



= Unused; always read "x"

Figure 12-34. Data Length Register (DLR) — Extended Identifier Mapping

Table 12-32. DLR Register Field Descriptions

Field	Description
3:0 DLC[3:0]	Data Length Code Bits — The data length code contains the number of bytes (data byte count) of the respective message. During the transmission of a remote frame, the data length code is transmitted as programmed while the number of transmitted data bytes is always 0. The data byte count ranges from 0 to 8 for a data frame. Table 12-33 shows the effect of setting the DLC bits.

15.1.4 Block Diagram

The block diagram for the RTC module is shown in Figure 15-2.

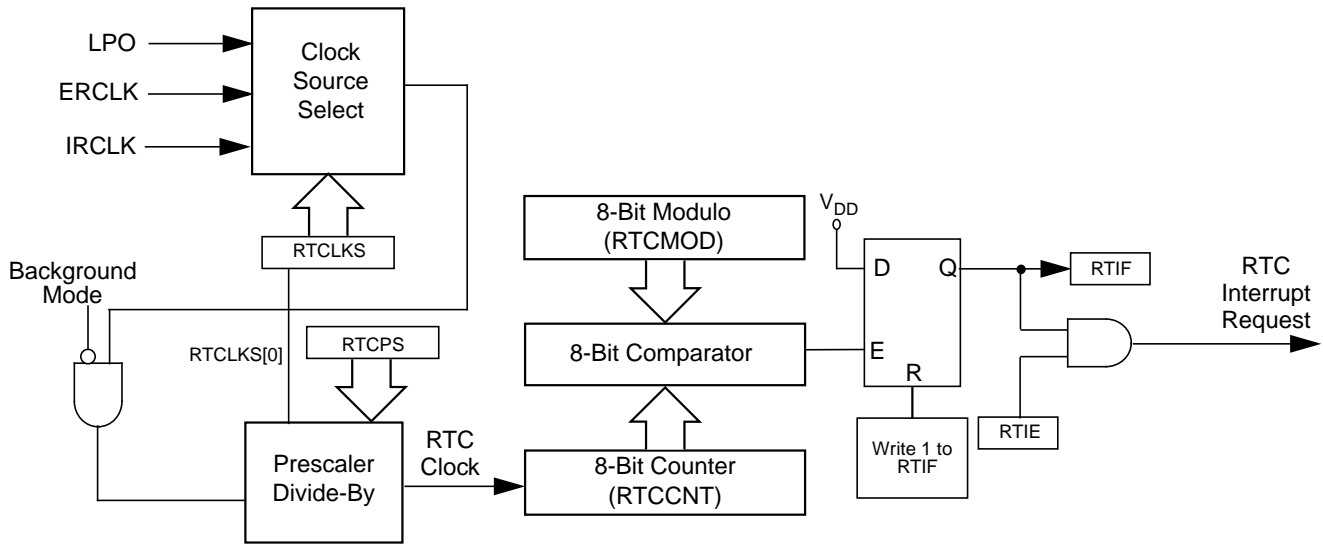


Figure 15-2. Real-Time Counter (RTC) Block Diagram

15.2 External Signal Description

The RTC does not include any off-chip signals.

15.3 Register Definition

The RTC includes a status and control register, an 8-bit counter register, and an 8-bit modulo register.

Refer to the direct-page register summary in the memory section of this document for the absolute address assignments for all RTC registers. This section refers to registers and control bits only by their names and relative address offsets.

Table 15-1 is a summary of RTC registers.

Table 15-1. RTC Register Summary

Name		7	6	5	4	3	2	1	0
RTCSC	R	RTIF	RTCLKS		RTIE	RTCPS			
	W								
RTCCNT	R	RTCCNT							
	W								
RTCMOD	R	RTCMOD							
	W								

RTCPS and the RTCLKS[0] bit select the desired divide-by value. If a different value is written to RTCPS, the prescaler and RTCCNT counters are reset to 0x00. Table 15-6 shows different prescaler period values.

Table 15-6. Prescaler Period

RTCPS	1-kHz Internal Clock (RTCLKS = 00)	1-MHz External Clock (RTCLKS = 01)	32-kHz Internal Clock (RTCLKS = 10)	32-kHz Internal Clock (RTCLKS = 11)
0000	Off	Off	Off	Off
0001	8 ms	1.024 ms	250 μ s	32 ms
0010	32 ms	2.048 ms	1 ms	64 ms
0011	64 ms	4.096 ms	2 ms	128 ms
0100	128 ms	8.192 ms	4 ms	256 ms
0101	256 ms	16.4 ms	8 ms	512 ms
0110	512 ms	32.8 ms	16 ms	1.024 s
0111	1.024 s	65.5 ms	32 ms	2.048 s
1000	1 ms	1 ms	31.25 μ s	31.25 ms
1001	2 ms	2 ms	62.5 μ s	62.5 ms
1010	4 ms	5 ms	125 μ s	156.25 ms
1011	10 ms	10 ms	312.5 μ s	312.5 ms
1100	16 ms	20 ms	0.5 ms	0.625 s
1101	0.1 s	50 ms	3.125 ms	1.5625 s
1110	0.5 s	0.1 s	15.625 ms	3.125 s
1111	1 s	0.2 s	31.25 ms	6.25 s

The RTC modulo register (RTCMOD) allows the compare value to be set to any value from 0x00 to 0xFF. When the counter is active, the counter increments at the selected rate until the count matches the modulo value. When these values match, the counter resets to 0x00 and continues counting. The real-time interrupt flag (RTIF) is set when a match occurs. The flag sets on the transition from the modulo value to 0x00. Writing to RTCMOD resets the prescaler and the RTCCNT counters to 0x00.

The RTC allows for an interrupt to be generated when RTIF is set. To enable the real-time interrupt, set the real-time interrupt enable bit (RTIE) in RTCSC. RTIF is cleared by writing a 1 to RTIF.

15.4.1 RTC Operation Example

This section shows an example of the RTC operation as the counter reaches a matching value from the modulo register.

16.3 Register Definition

This section consists of register descriptions in address order.

16.3.1 TPM Status and Control Register (TPMxSC)

TPMxSC contains the overflow status flag and control bits used to configure the interrupt enable, TPM configuration, clock source, and prescale factor. These controls relate to all channels within this timer module.

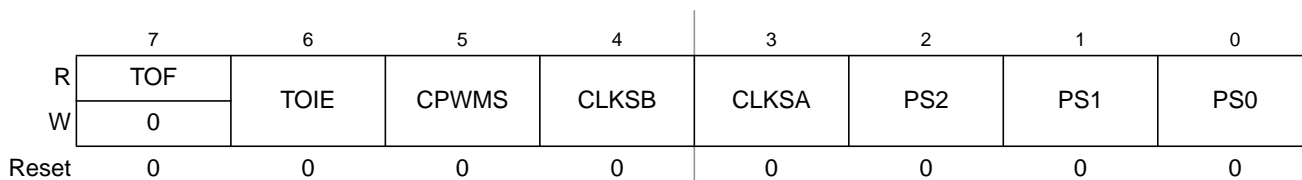


Figure 16-7. TPM Status and Control Register (TPMxSC)

Table 16-2. TPMxSC Field Descriptions

Field	Description
7 TOF	<p>Timer overflow flag. This read/write flag is set when the TPM counter resets to 0x0000 after reaching the modulo value programmed in the TPM counter modulo registers. Clear TOF by reading the TPM status and control register when TOF is set and then writing a logic 0 to TOF. If another TPM overflow occurs before the clearing sequence is complete, the sequence is reset so TOF would remain set after the clear sequence was completed for the earlier TOF. This is done so a TOF interrupt request cannot be lost during the clearing sequence for a previous TOF. Reset clears TOF. Writing a logic 1 to TOF has no effect.</p> <p>0 TPM counter has not reached modulo value or overflow 1 TPM counter has overflowed</p>
6 TOIE	<p>Timer overflow interrupt enable. This read/write bit enables TPM overflow interrupts. If TOIE is set, an interrupt is generated when TOF equals one. Reset clears TOIE.</p> <p>0 TOF interrupts inhibited (use for software polling) 1 TOF interrupts enabled</p>
5 CPWMS	<p>Center-aligned PWM select. When present, this read/write bit selects CPWM operating mode. By default, the TPM operates in up-counting mode for input capture, output compare, and edge-aligned PWM functions. Setting CPWMS reconfigures the TPM to operate in up/down counting mode for CPWM functions. Reset clears CPWMS.</p> <p>0 All channels operate as input capture, output compare, or edge-aligned PWM mode as selected by the MSnB:MSnA control bits in each channel's status and control register. 1 All channels operate in center-aligned PWM mode.</p>
4–3 CLKS[B:A]	<p>Clock source selects. As shown in Table 16-3, this 2-bit field is used to disable the TPM system or select one of three clock sources to drive the counter prescaler. The fixed system clock source is only meaningful in systems with a PLL-based or FLL-based system clock. When there is no PLL or FLL, the fixed-system clock source is the same as the bus rate clock. The external source is synchronized to the bus clock by TPM module, and the fixed system clock source (when a PLL or FLL is present) is synchronized to the bus clock by an on-chip synchronization circuit. When a PLL or FLL is present but not enabled, the fixed-system clock source is the same as the bus-rate clock.</p>
2–0 PS[2:0]	<p>Prescale factor select. This 3-bit field selects one of 8 division factors for the TPM clock input as shown in Table 16-4. This prescaler is located after any clock source synchronization or clock source selection so it affects the clock source selected to drive the TPM system. The new prescale factor will affect the clock source on the next system clock cycle after the new value is updated into the register bits.</p>

Appendix B

Timer Pulse-Width Modulator (TPMV2)

NOTE

This chapter refers to S08TPM version 2, which applies to the 3M05C and older mask sets of this device.)M74K and newer mask set devices use S08TPM version 3. If your device uses mask 0M74K or newer, please refer to [Chapter 16, “Timer Pulse-Width Modulator \(S08TPMV3\) for information pertaining to that module.](#)

The TPM uses one input/output (I/O) pin per channel, TPMxCHn where x is the TPM number (for example, 1 or 2) and n is the channel number (for example, 0–4). The TPM shares its I/O pins with general-purpose I/O port pins (refer to the [Pins and Connections](#) chapter for more information).

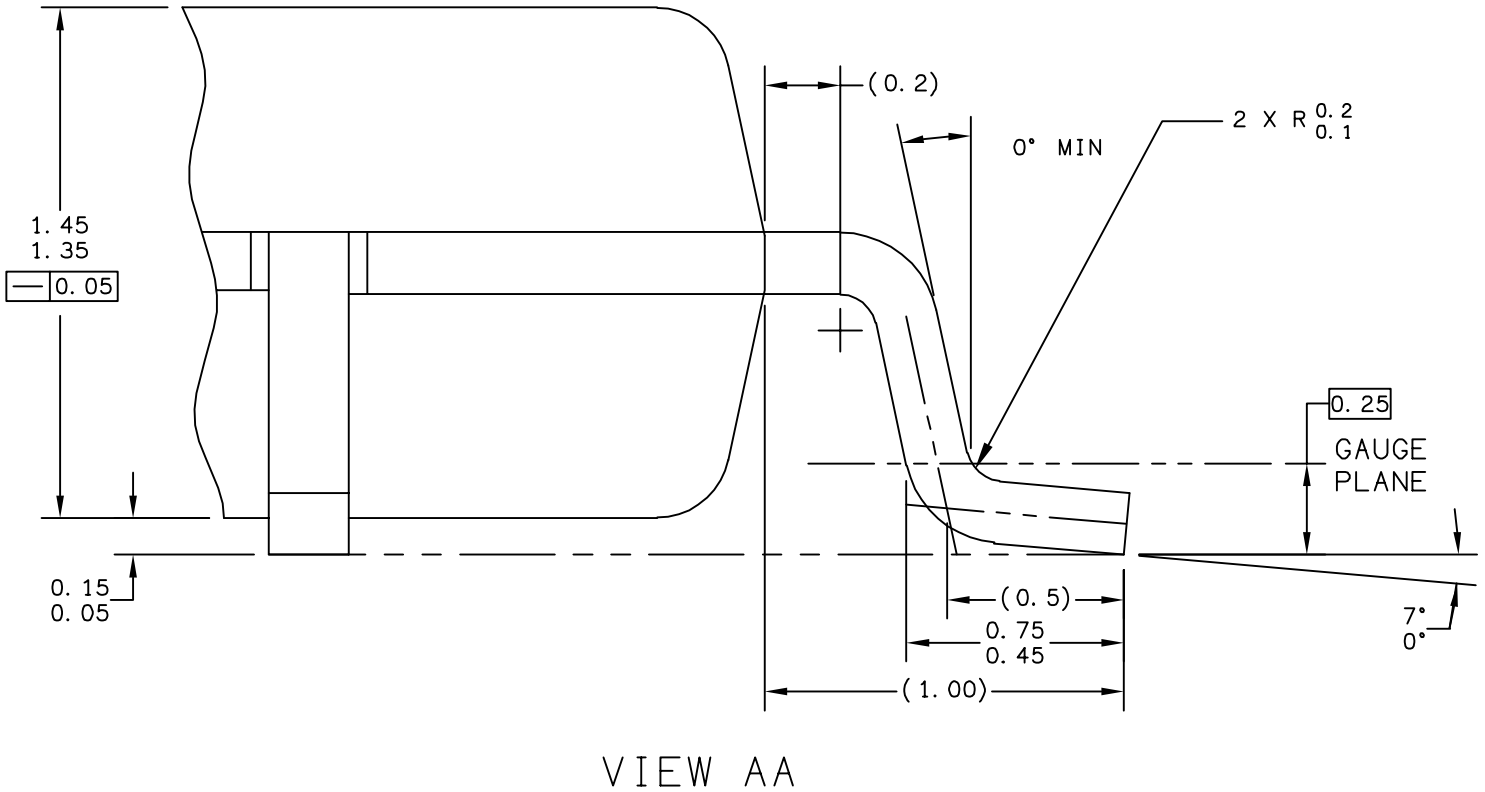
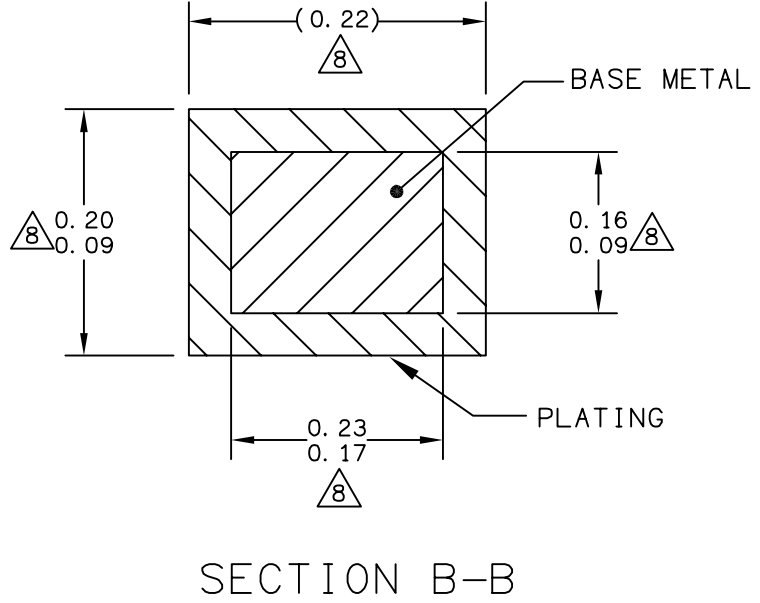
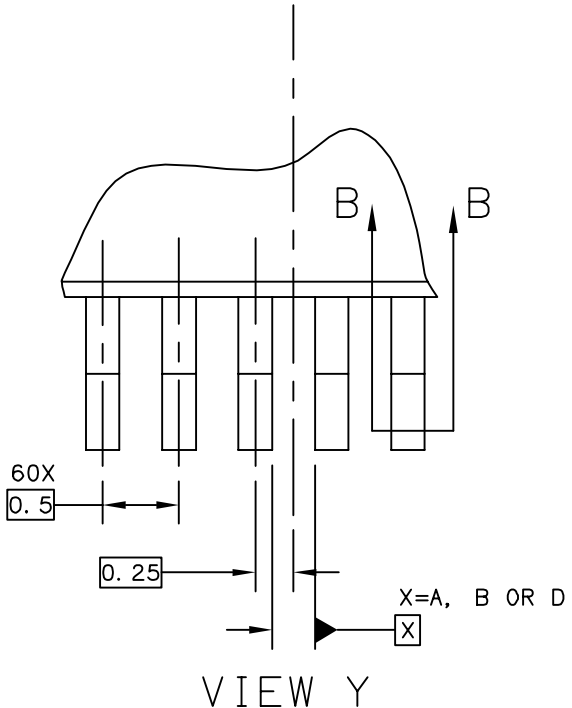
B.0.1 Features

The TPM has the following features:

- Each TPM may be configured for buffered, center-aligned pulse-width modulation (CPWM) on all channels
- Clock sources independently selectable per TPM (multiple TPMs device)
- Selectable clock sources (device dependent): bus clock, fixed system clock, external pin
- Clock prescaler taps for divide by 1, 2, 4, 8, 16, 32, 64, or 128
- 16-bit free-running or up/down (CPWM) count operation
- 16-bit modulus register to control counter range
- Timer system enable
- One interrupt per channel plus a terminal count interrupt for each TPM module (multiple TPMs device)
- Channel features:
 - Each channel may be input capture, output compare, or buffered edge-aligned PWM
 - Rising-edge, falling-edge, or any-edge input capture trigger
 - Set, clear, or toggle output compare action
 - Selectable polarity on PWM outputs

B.0.2 Block Diagram

[Figure B-1](#) shows the structure of a TPM. Some MCUs include more than one TPM, with various numbers of channels.



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TITLE: 64LD LQFP, 10 X 10 X 1.4 PKG, 0.5 PITCH, CASE OUTLINE	DOCUMENT NO: 98ASS23234W	REV: E	
	CASE NUMBER: 840F-02	11 AUG 2006	
	STANDARD: JEDEC MS-026 BCD		